

DESCRIPTION

The IRFR5305 is P channel enhancement mode power effect transistor which is produced using high cell density advanced trench technology. The high density process is especially able to minize on-state resistance. These devices are. especially suited for low voltage application power management DC-DC converters.

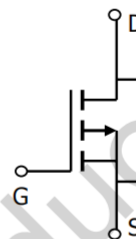
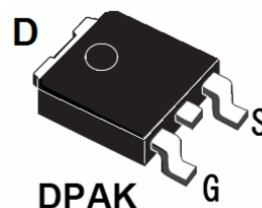
FEATURE

- ◆ -60V/-26 A, $R_{DS(ON)}=16\text{ m}\Omega(\text{typ.})@V_{GS}=-10\text{V}$
- ◆ -60V/-20A, $R_{DS(ON)}=25\text{ m}\Omega(\text{typ.})@V_{GS}=-4.5\text{V}$
- ◆ Super high design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and Maximum DC current capability
- ◆ Full RoHS compliance
- ◆ TO252 package design
- ◆ 100% UIS Tested
- ◆ 100% Rg tested

APPLICATIONS

- ◆ Power Management
- ◆ DC/DC Converter
- ◆ Load Switch

PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Parameter		Symbol	Maximum		Units	
Drain-Source Voltage		V_{DS}	-60		V	
Gate-Source Voltage		V_{GS}	± 20		V	
Continuous Drain Current ^G	$T_C=25^{\circ}\text{C}$	I_D	-26		A	
	$T_C=100^{\circ}\text{C}$		-18			
Pulsed Drain Current ^C			I_{DM}	-60		
Avalanche Current ^C		I_{AR}	-26		A	
Repetitive avalanche energy $L=0.1\text{mH}$ ^C		E_{AR}	33.8		mJ	
Power Dissipation ^B	$T_C=25^{\circ}\text{C}$	P_D	60		W	
	$T_C=100^{\circ}\text{C}$		30			
Power Dissipation ^A	$T_A=25^{\circ}\text{C}$	P_{DSM}	2.5		W	
	$T_A=70^{\circ}\text{C}$		1.6			
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175		$^{\circ}\text{C}$	
Thermal Characteristics						
Parameter		Symbol	Typ		Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10\text{s}$	$R_{\theta JA}$	16.7	25		$^{\circ}\text{C/W}$
Maximum Junction-to-Ambient ^A	Steady-State		40	50		$^{\circ}\text{C/W}$
Maximum Junction-to-Case ^C	Steady-State	$R_{\theta JC}$	1.9	2.5		$^{\circ}\text{C/W}$

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress rating only and functional device operation is not implied

■ **ELECTRICAL CHARACTERISTICS** ($T_A=25^{\circ}\text{C}$ Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D= -250\mu A$	-60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D= -250\mu A$	-1.0		-2.5	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-60V, V_{GS}=0$			-1	μA
		$V_{DS}=-60V, V_{GS}=0$ $T_J=85^{\circ}C$			-5	
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS}=-10V, I_D= -20\text{ A}$		16	20	m Ω
		$V_{GS}= -4.5V, I_D= -20\text{ A}$		20	23	
Source-Drain Diode						
V_{SD}	Diode Forward Voltage	$I_S= -1\text{ A}, V_{GS}=0V$		0.7	1.3	V
Dynamic Parameters						
Q_g	Total Gate Charge	$V_{DS}= -30V$ $V_{GS}= -10V$ $I_D=-20\text{ A}$		53		nC
Q_{gs}	Gate-Source Charge			12		
Q_{gd}	Gate-Drain Charge			13		
C_{iss}	Input Capacitance	$V_{DS}= -30V$ $V_{GS}=0V$ $f=1MHz$		1886		pF
C_{oss}	Output Capacitance			540		
C_{rss}	Reverse Transfer Capacitance			240		
$T_{d(on)}$	Turn-On Time	$V_{DS}= -30V$ $R_L=1.50\Omega$ $V_{GEN}= -10V$ $R_G=3.0\Omega$		19		nS
T_r				15		
$T_{d(off)}$	Turn-Off Time			52		
T_f				17		

Note: 1. Pulse test: pulse width $\leq 300\mu\text{S}$, duty cycle $\leq 2\%$

2.Static parameters are based on package level with recommended wire bonding

■ **TYPICAL CHARACTERISTICS** (25°C Unless Note)

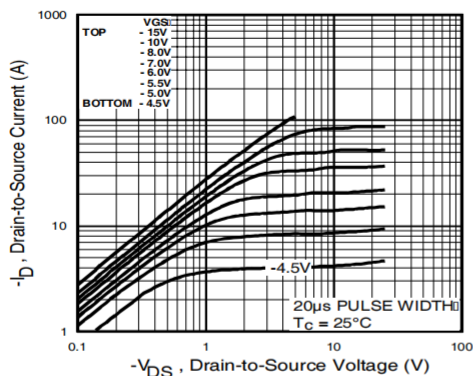


Fig 1. Typical Output Characteristics

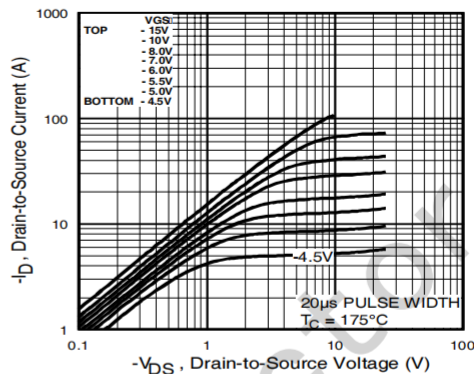


Fig 2. Typical Output Characteristics

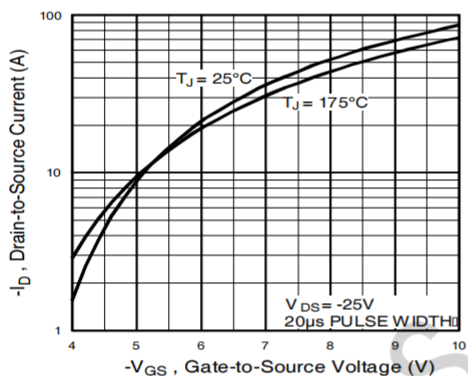


Fig 3. Typical Transfer Characteristics

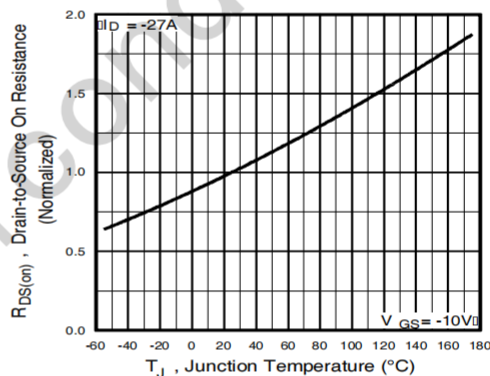


Fig 4. Normalized On-Resistance Vs. Temperature

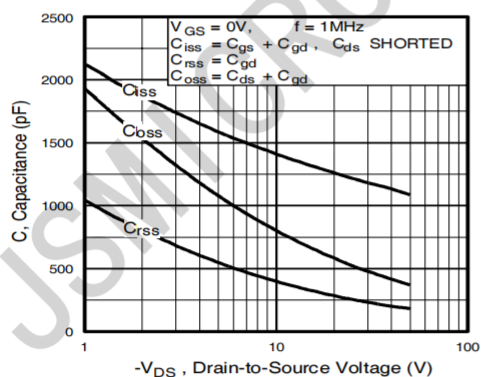


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

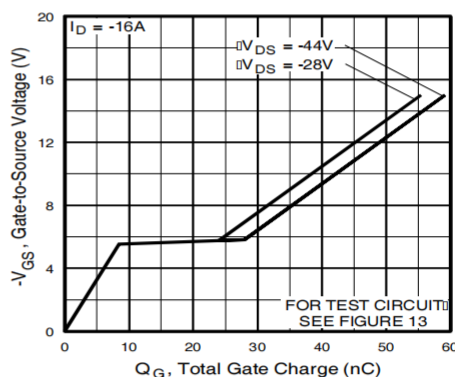


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

■ TYPICAL CHARACTERISTICS (continuous)

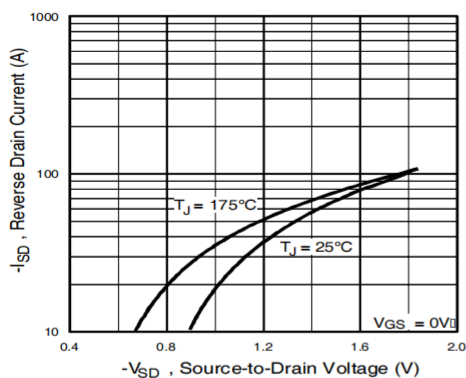


Fig 7. Typical Source-Drain Diode Forward Voltage

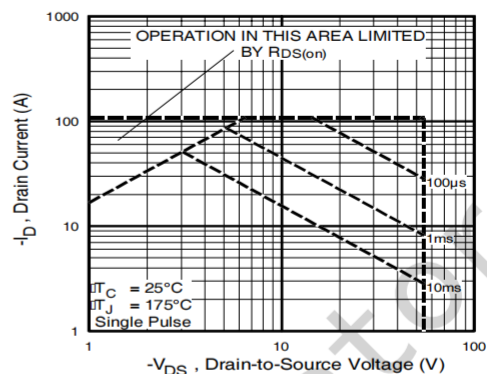


Fig 8. Maximum Safe Operating Area

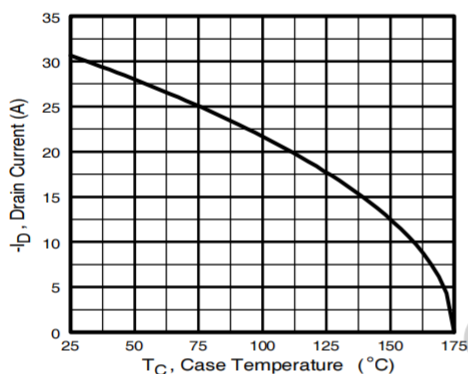


Fig 9. Maximum Drain Current Vs. Case Temperature

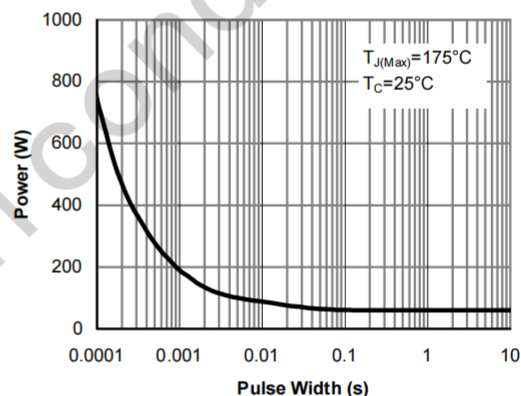
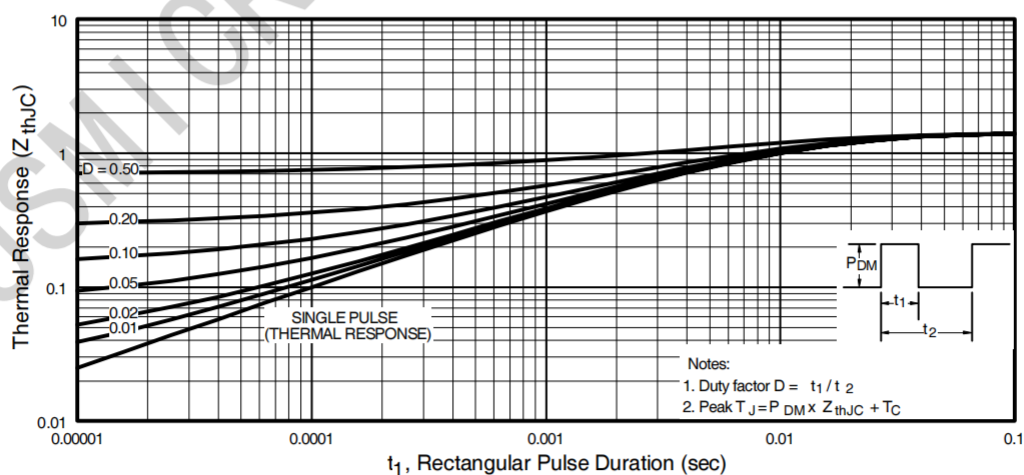
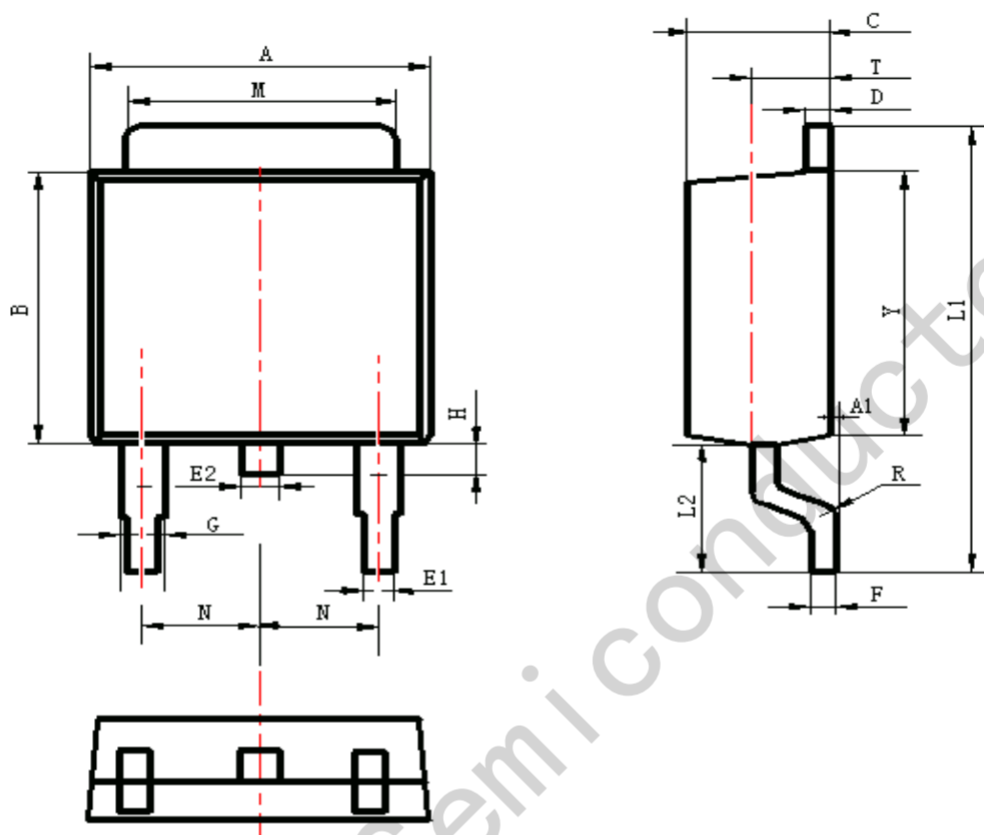


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)



Package Information

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	6.30	6.90	0.248	0.272
A1	0.00	0.16	0.000	0.006
B	5.70	6.30	0.224	0.248
C	2.10	2.50	0.083	0.098
D	0.30	0.70	0.012	0.028
E1	0.60	0.90	0.024	0.035
E2	0.70	1.00	0.028	0.039
F	0.30	0.60	0.012	0.024
G	0.70	1.20	0.028	0.047
L1	9.60	10.50	0.378	0.413
L2	2.70	3.10	0.106	0.122
H	0.40	1.00	0.016	0.039
M	5.10	5.50	0.201	0.217
N	2.09	2.49	0.082	0.098
R	0.30		0.012	
T	1.40	1.60	0.055	0.063
Y	5.10	6.30	0.201	0.248